

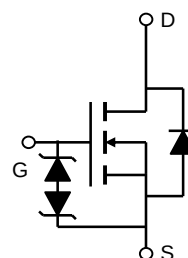
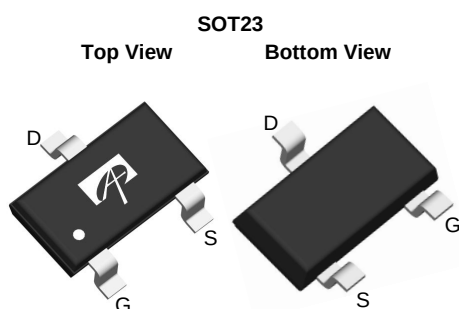
General Description

The AO3460 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge, and operation with gate voltages as low as 4.5V, in the small SOT-23 footprint. It can be used for a wide variety of applications, including load switching, low current inverters and low current DC-DC converters. It is ESD protected.

Product Summary

V_{DS} (V) = 60V
 I_D = 0.65A (V_{GS} = 10V)
 $R_{DS(ON)} < 1.7\Omega$ (V_{GS} = 10V)
 $R_{DS(ON)} < 2\Omega$ (V_{GS} = 4.5V)

ESD protected



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^{A, F}	I_D	0.65	A
		0.5	
Pulsed Drain Current ^B	I_{DM}	1.6	
Power Dissipation ^A	P_D	1.4	W
		0.9	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	70	90	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^A		100	125	$^\circ\text{C/W}$
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	63	80	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	60			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V			1	μA
		T _J =55℃			5	
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250uA	1	2.2	2.5	V
I _{D(ON)}	On state drain current	V _{GS} =10V, V _{DS} =5V	1.6			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =0.65A		1.4	1.7	Ω
		T _J =125℃		2.5	3	
			V _{GS} =4.5V, I _D =0.5A		1.6	2
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =0.65A		0.8		S
V _{SD}	Diode Forward Voltage	I _S =0.1A,V _{GS} =0V		0.8	1	V
I _S	Maximum Body-Diode Continuous Current				1.2	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, f=1MHz		22	27	pF
C _{oss}	Output Capacitance			6		pF
C _{rss}	Reverse Transfer Capacitance			2		pF
SWITCHING PARAMETERS						
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =30V, R _L =75Ω, R _{GEN} =3Ω		5.3		ns
t _r	Turn-On Rise Time			2.8		ns
t _{D(off)}	Turn-Off DelayTime			19.7		ns
t _f	Turn-Off Fall Time			5.5		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =0.65A, dI/dt=100A/μs, V _{GS} =-9V		11.3	14	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =0.65A, dI/dt=100A/μs, V _{GS} =-9V		7.5		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The SOA curve provides a single pulse rating.

F: The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

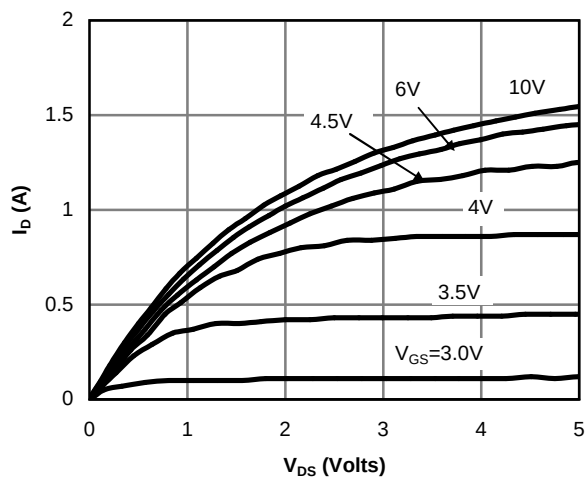


Figure 1: On-Region Characteristics

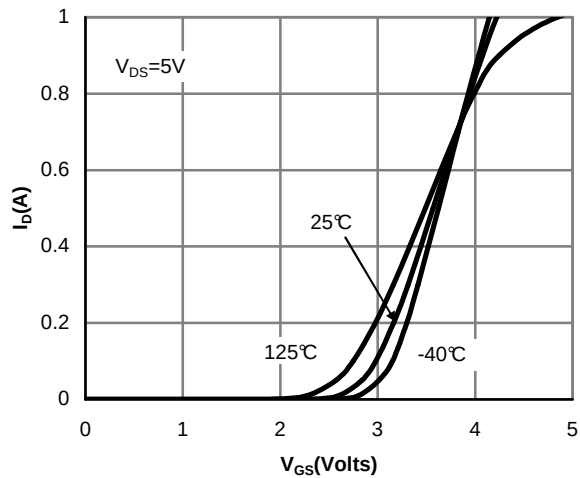


Figure 2: Transfer Characteristics

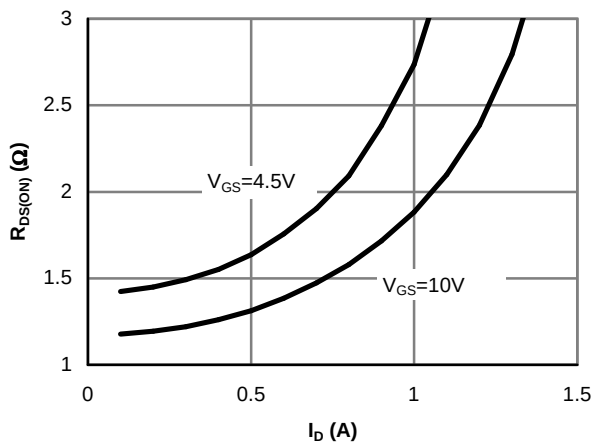


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

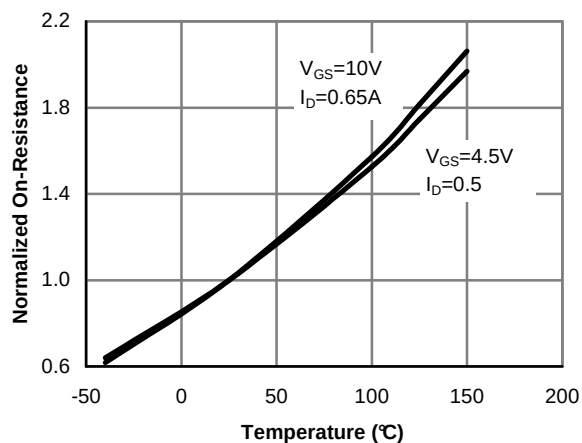


Figure 4: On-Resistance vs. Junction Temperature

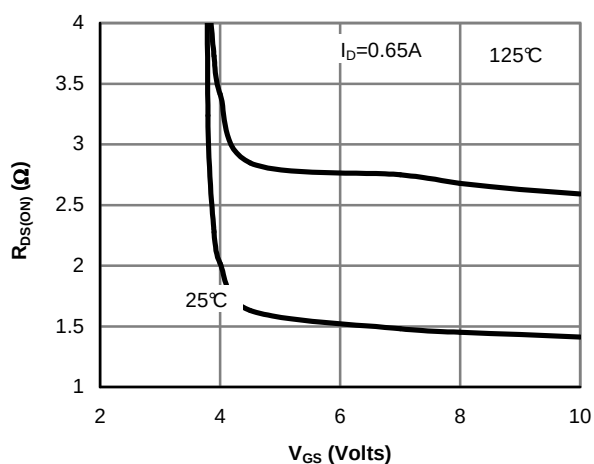


Figure 5: On-Resistance vs. Gate-Source Voltage

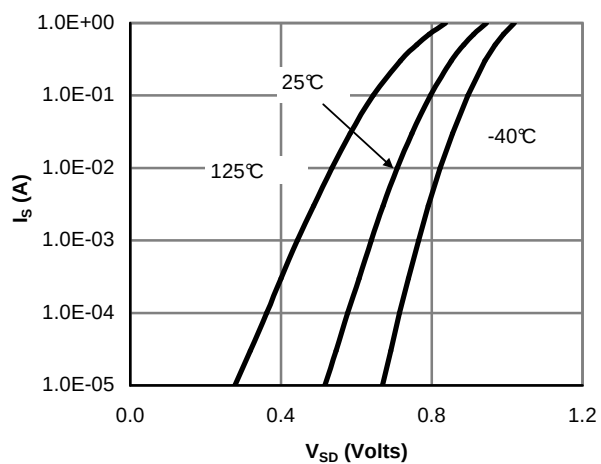


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

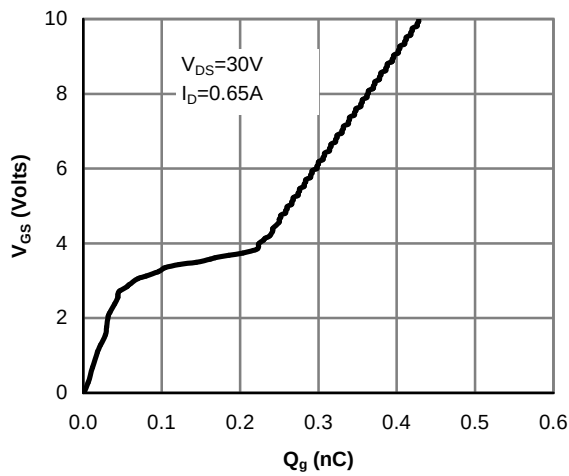


Figure 7: Gate-Charge Characteristics

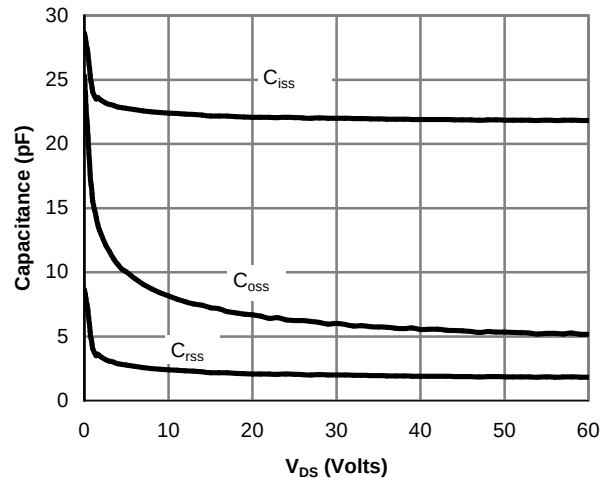


Figure 8: Capacitance Characteristics

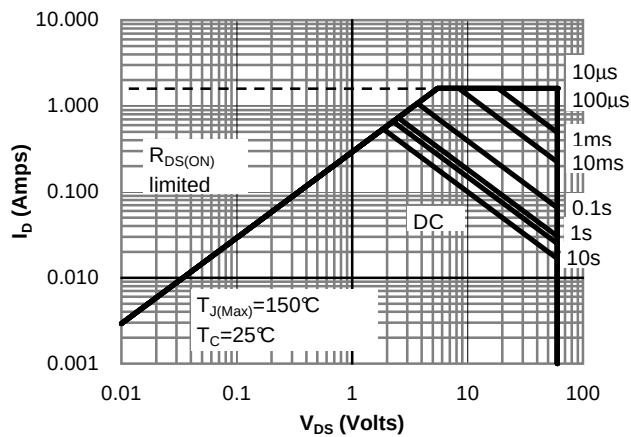


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

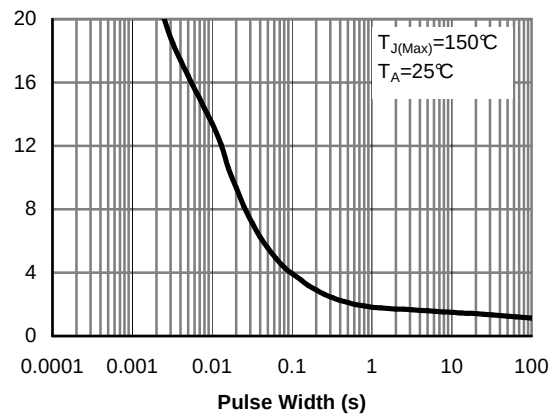


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

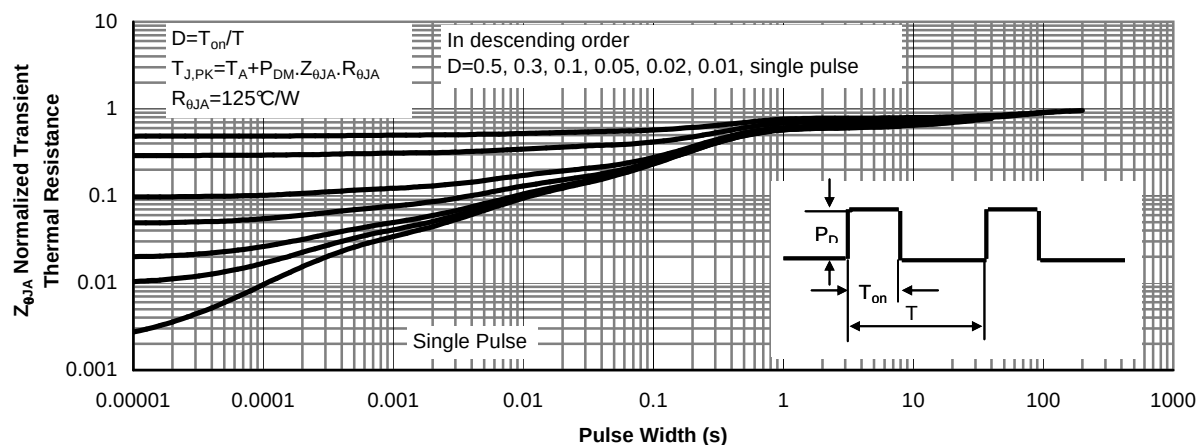


Figure 11: Normalized Maximum Transient Thermal Impedance